

11/30/01

Class	Subclass	ISSUE CLASSIFICATION
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# U.S. UTILITY Patent Application

**O.I.P.E.**

PATENT DATE

O.I.P.E.  
SCANNED TR2 Q.A. *HT*

APPLICATION NO.  
09/996802

CONT/PRIOR  
F

CLASS  
428

SUBCLASS  
413

ART UNIT 1712  
~~1773~~

**EXAMINER**

## APPLICANTS

Tetsuro Sato  
Tsutomu Asai

## TITLE

Resin compound for fabricating interlayer dielectric of printed wiring board, resin sheet and resin applied-copper foil for forming insulating layer using the resin compound, and copper-clad laminate using them

PTO-2040  
12/99

# ISSUING CLASSIFICATION

[illegible]

☐ Continued on Issue Slip Inside File Jacket

<b>TERMINAL DISCLAIMER</b>	<b>DRAWINGS</b>			<b>CLAIMS ALLOWED</b>	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) (Date)			<b>NOTICE OF ALLOWANCE MAILED</b>	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____				_____ (Primary Examiner) (Date)	
				<b>ISSUE FEE</b>	
				Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) (Date)			<b>ISSUE BATCH NUMBER</b>	

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